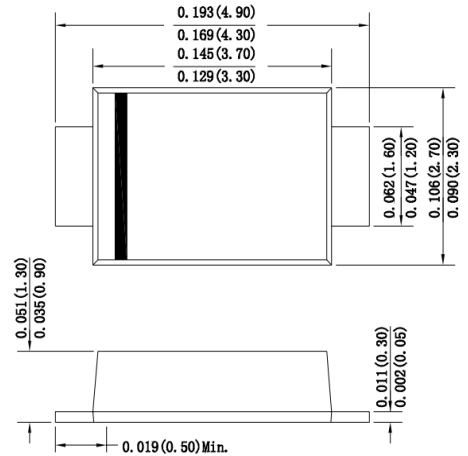


### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals

**SMAF**



Dimensions in inches and (millimeters)

### Mechanical Data

**Case** : Molded plastic body

**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.0014 ounce, 0.038 grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	E1AF	E1BF	E1CF	E1DF	E1FF	E1GF	E1JF	UNITS	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V	
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V	
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V	
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.0							A	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	30.0							A	
Maximum instantaneous forward voltage at 1.0A	$V_F$	0.95				1.25		1.7	V	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	5.0				500				$\mu\text{A}$
Maximum reverse recovery time(Note 1)	$T_{rr}$	35				ns				
Typical junction capacitance (Note2)	$C_J$	18.0				pF				
Typical thermal resistance	$R_{qJA}$	70.0				$^\circ\text{C/W}$				
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$	

**Note:** 1.Reverse recovery time test condition:  $I_F=0.5\text{A}$   $I_R=1.0\text{A}$   $I_{rr}=0.25\text{A}$   
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

### Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

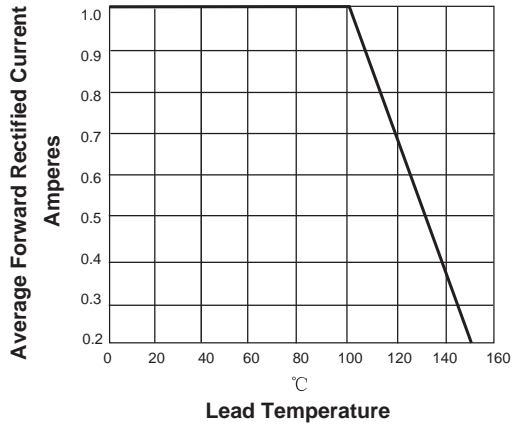


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

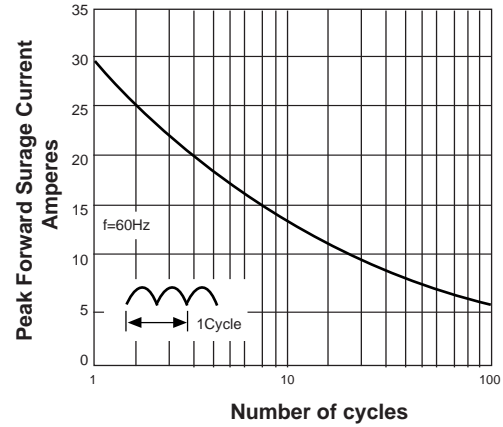


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

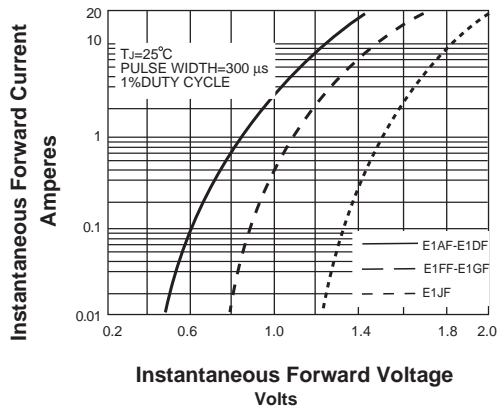
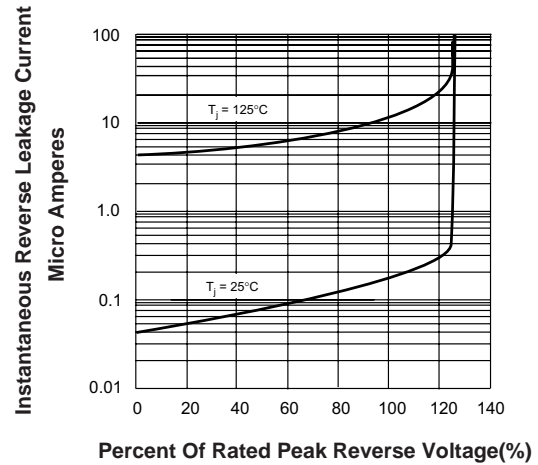
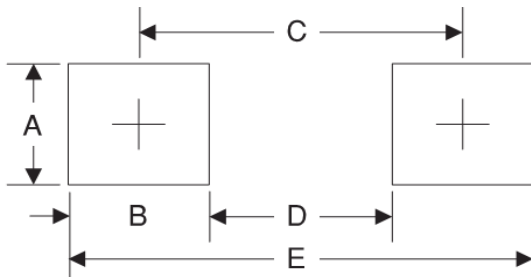


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

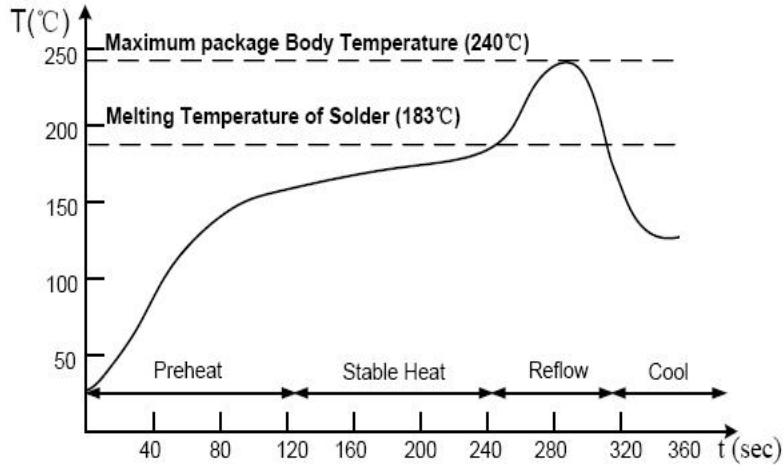


### Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.00	0.078
E	5.10	0.200

### Suggested Soldering Temperature Profile

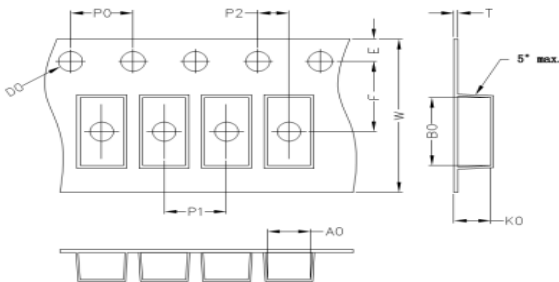


**Note**

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### Package Information

**Carrier Dimension(mm)**



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
2.83	4.75	1.42	1.55	1.75	5.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	4.0	2.0	0.25	12	0.1

**Package Specifications**

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMAF	7'	178	3	180	12	380*200*200	120
	11'	278	7.5	285	15	355*310*310	120